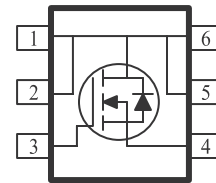
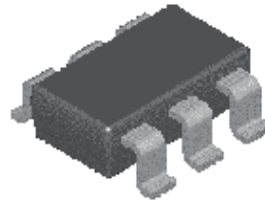


## N-Channel 30V (D-S) MOSFET

These miniature surface mount MOSFETs utilize High Cell Density process. Low  $r_{DS(on)}$  assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are power switch, power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low  $r_{DS(on)}$  Provides Higher Efficiency and Extends Battery Life
- Low Gate Charge
- Fast Switch
- Miniature TSOP-6 Surface Mount Package Saves Board Space

PRODUCT SUMMARY		
$V_{DS}$ (V)	$r_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
30	0.044 @ $V_{GS} = 10\text{ V}$	5.1
	0.064 @ $V_{GS} = 4.5\text{ V}$	4.5



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current <sup>a</sup>	$T_A = 25^\circ\text{C}$	$I_D$	5.5	A
	$T_A = 70^\circ\text{C}$		4.4	
Pulsed Drain Current <sup>b</sup>		$I_{DM}$	$\pm 20$	
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	1.3	A
Power Dissipation <sup>a</sup>	$T_A = 25^\circ\text{C}$	$P_D$	2.0	W
	$T_A = 70^\circ\text{C}$		1.3	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient <sup>a</sup>	$t \leq 5\text{ sec}$	$R_{THJA}$	85	$^\circ\text{C/W}$
	Steady-State		62.5	

#### Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

**SPECIFICATIONS ( $T_A = 25^\circ\text{C}$  UNLESS OTHERWISE NOTED)**

Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Switch Off Characteristics						
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±20 V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V			1	uA
		V <sub>DS</sub> = 24 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55°C			10	
Switch On Characteristics						
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 uA	1.0			V
Drain-Source On-Resistance <sup>A</sup>	r <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.1 A			44	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.1 A T <sub>J</sub> = 55°C			49	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4.5 A			64	
Forward Tranconductance <sup>A</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5.1 A		45		S
On-State Drain Current <sup>A</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	20			A
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1.3 A, V <sub>GS</sub> = 0 V		0.75		V
Dynamic <sup>b</sup>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 5 V, I <sub>D</sub> = 5.1 A R <sub>L</sub> = 6 Ω		4.0		nC
Gate-Source Charge	Q <sub>gs</sub>			1.1		
Gate-Drain Charge	Q <sub>gd</sub>			1.4		
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> = 15 V, R <sub>L</sub> = 6 Ω, I <sub>D</sub> = 1 A, V <sub>GEN</sub> = 10 V		6		ns
Rise Time	t <sub>r</sub>			10		
Turn-Off Delay Time	t <sub>d(off)</sub>			18		
Fall-Time	t <sub>f</sub>			5		

## Notes

- Pulse test:  $PW \leq 300\mu\text{s}$  duty cycle  $\leq 2\%$ .
- Guaranteed by design, not subject to production testing.